Daxin Materials Corporation

Investor Conference

2026 Q3 | 2026.11.16

Semiconductor Materials | Display Materials | Key Raw Materials



A Materials Design House and More

Disclaimer

1. This presentation contains forward-looking statements based on information currently available to the Company. Actual results may differ materially from those contained in the forward-looking statements due to significant risks and uncertainties.

2. The outlook presented herein is based on the Company’s current expectations and projections about future events. Except as required by law, the Company undertakes no obligation to update or revise any forward-looking statement.

3. The financial figures in this presentation are prepared in accordance with International Financial Reporting Standards (IFRS). The third-quarter 2026 figures have been reviewed by independent auditors.

Agenda

01 Financial Results

02 Growth Drivers

03 Competitiveness

04 Outlook

20 years of expertise in materials
Expanding into diversified product lines



Foundation	July 2006
IPO on TAIEX	July 2012 (ticker: 5234)
Paid-in capital	NT$1,027million
Employees	>450, over half in R&D
2025 revenue	NT$4,630 million
Patents granted	341 (471 filed in total)

70.9%
3Q26 revenue proportion

Display Materials
LCD materials (CF, Cell, Array)
Micro LED and EPD materials

27.1%
3Q26 revenue proportion

Semiconductor Materials
Wafer process (advanced & mature)
Advanced packaging (2.5D/3D IC)

2.0%
3Q26 revenue proportion

Key Raw Materials and others
Monomers, polymers & others (electronics, semiconductors, green energy)

01 Financial Results

01 Financial Results
02 Growth Drivers
03 Competitiveness
04 Outlook



3Q26 revenue reached an all-time high

3Q26 vs. 3Q25

Revenue	Gross margin %	Operating income
NT$1,382M	**41.3%**	**NT$274M**
YoY +16.5% | QoQ +7.8%	YoY +1.6 ppts (3Q25: 39.7%)	YoY +31.1% (3Q25: 209M)
Net income	**EPS**	**Semiconductor materials revenue %**
NT$235M	**NT$2.29**	**27.1%**
YoY +20.0% (3Q25: NT$196M)	3Q25: NT$1.90	3Q25: 19.0%

Record revenue and an expanding share of semiconductor material propelled profit growth ahead of revenue.

Note: YoY = year-over-year; QoQ = quarter-over-quarter

Revenue and profitability

Unit: NT$M; EPS in NT$

Item	3Q26	2Q26	3Q25	QoQ	YoY	YTD 3Q26	YTD 3Q25	YoY
Revenue	1,381.9	1,281.7	1,186.2	7.8%	16.5%	3,864.9	3,443.4	12.2%
Gross profit	570.1	549.9	470.6	3.7%	21.1%	1,637.8	1,389.9	17.8%
Gross margin %	41.3%	42.9%	39.7%	-1.6 ppts	+1.6 ppts	42.4%	40.4%	+2.0 ppts
Operating income	**274.5**	**257.5**	**209.4**	**6.6%**	**31.1%**	**773.3**	**636.5**	**21.5%**
Operating margin %	19.9%	20.1%	17.6%	-0.2 ppts	+2.3 ppts	20.0%	18.5%	+1.5 ppts
Net income	**234.9**	**228.8**	**195.8**	**2.7%**	**20.0%**	**690.8**	**548.0**	**26.1%**
EPS	**2.29**	**2.23**	**1.90**	**2.7%**	**20.5%**	**6.73**	**5.33**	**26.3%**

profit growth outpaced revenue growth

Revenue YTD 3Q26, up 12.2% YoY | operating income, up 21.5% YoY | net income after tax, up 26.1% YoY

Financial structure and working capital

Unit: NT$M

Item	3Q26	2Q26	3Q25
Cash & time deposits	990	1,142	1,380
Inventory	495	482	387
Net PP&E	1,529	1,542	1,449
Total assets	**5,245**	**4,841**	**4,837**
Total liabilities	1,694	1,526	1,519
Total equity	**3,551**	**3,315**	**3,318**
Current ratio	246%	236%	258%

YTD 3Q26 operating cash flow

NT$431M

YTD 3Q25 NT$546M

YTD 3Q26 CAPEX

NT$250M

YTD 3Q25 : NT$165M

Inventory turnover days

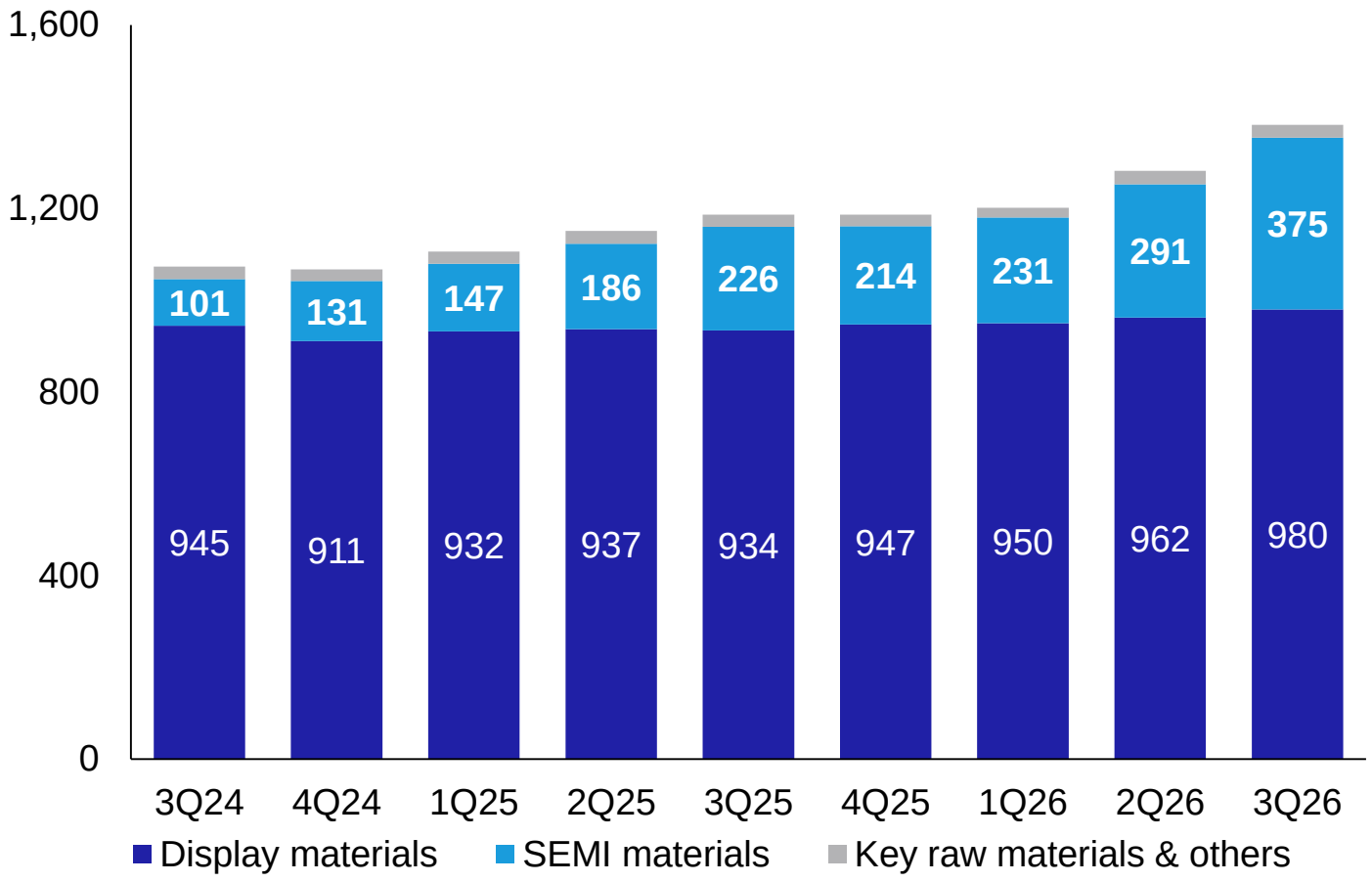
56 days

2Q26: 58 days

Note: Cash & time deposits include time deposits with maturities over three months.

Semiconductor materials serve as a key growth engine

Quarterly revenue, NT$M



NT$896M

YTD 3Q26 semiconductor revenue (YoY +60.3%)

19.0% → 27.1%

Semiconductor materials % (3Q25 → 3Q26)

around 50 : 50

Advanced packaging vs. Advanced process mix

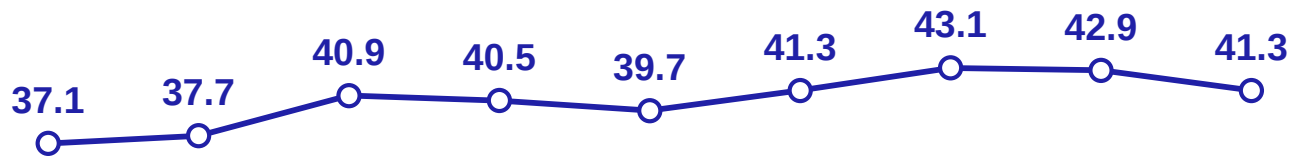
around 30%

4Q26 semiconductor materials % (F)

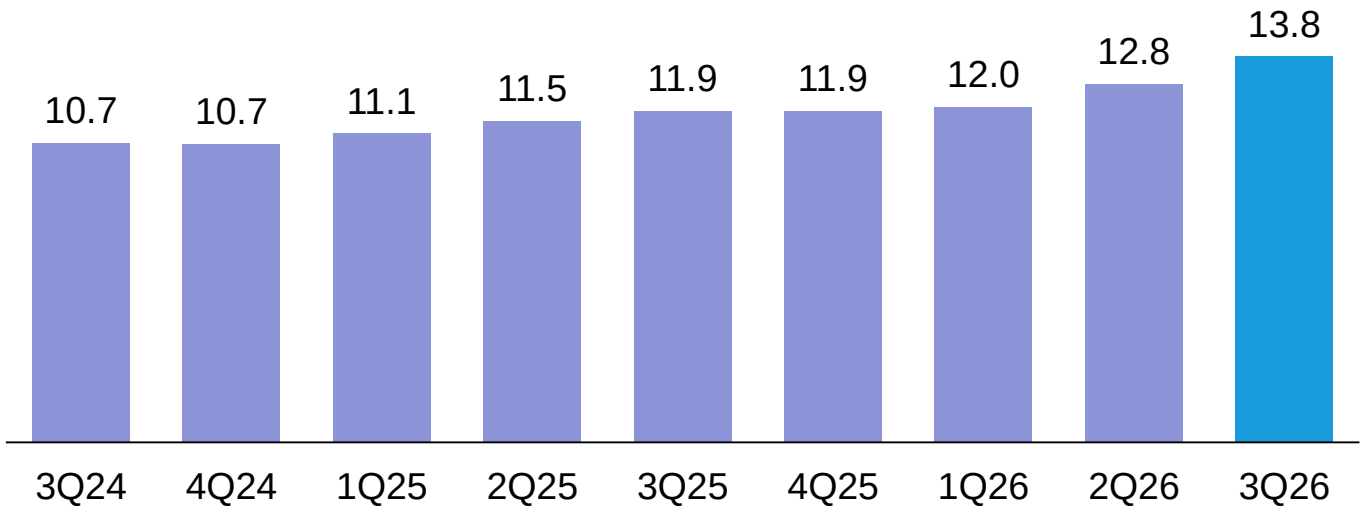
Revenue grew as gross margin improved

Gross margin and revenue, quarterly

Gross margin (%)



Revenue (NT$100M)



1 Semiconductor materials account for a larger revenue %

3Q25 19.0% → 3Q26 27.1%; a better product mix lifted gross margin rate

2 Product portfolio & cost optimization

Scaled back low-margin products; key monomers and polymers synthesized in-house

3 Near-term risks: Raw material prices, FX

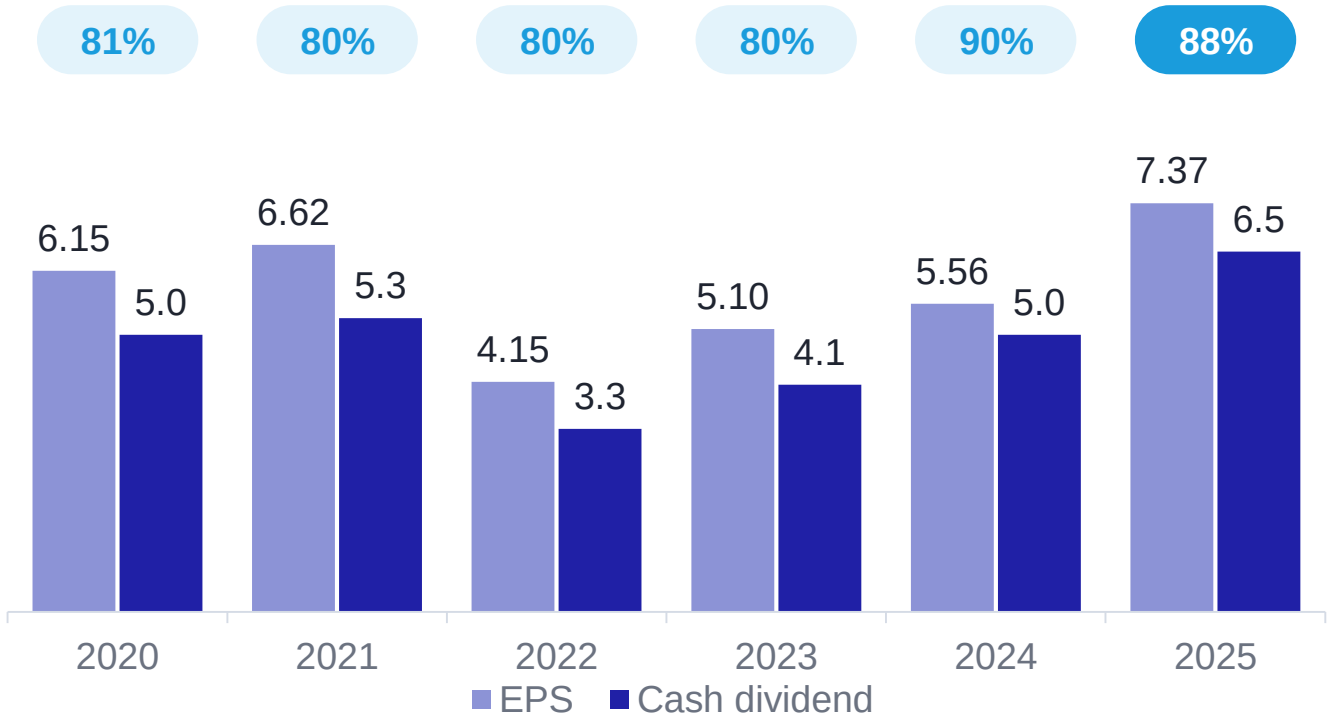
Gross margin %

(YTD 3Q25 → YTD 3Q26)

40.4% → 42.4%

The stable dividend policy, balanced with CAPEX

EPS and cash dividend, NT$ (payout ratio shown above)



Semiconductor materials mix

Lifts overall profitability

Disciplined CAPEX

Capacity tied to customer qualification; D&A accounts for 5–6% of revenue.

02 Growth Drivers



Three-Phase Development Strategy: From Display to SEMI and Advanced Materials Platforms

From LCD materials to advanced semiconductor processes and advanced packaging, Daxin aims to build an integrated platform spanning materials, processes, and equipment—continuously improving overall profitability and creating sustainable long-term shareholder value.

Global Leader

Photo Spacer Market Share

DAXIN 1.0

Display Materials 2006–2016

LCD materials development and mass production

Global leadership in PS and PSA PI

23.2%

SEMI revenue as a share of total revenue, 9M 2026 (2025: 16.7%)

DAXIN 2.0

SEMI Materials 2016–2026

Entered the advanced-packaging release-layer market

Expanded into advanced wafer processes

Shipments commenced in 2018

> 50%

Target SEMI revenue contribution by 2030

DAXIN 3.0

Materials Solutions 2026–

Expanding from advanced processes into materials, processes, equipment, and testing to provide integrated materials solutions

Strategic partnerships and materials foundry model

Early-stage collaboration with equipment suppliers

*Semiconductor (SEMI)

Growing Semiconductor Materials Demand with a Clear Trend Toward Localization

Global SEMI Materials

US$142.4 Billion

2035 Market Size

2025–2035 CAGR: +5.2%

Wet Chemicals

US$8.8 Billion

2035 Market Size

2025–2035 CAGR: +6.8%

Advanced Packaging Market

US$88.6 Billion

2035 Market Size

2025–2035 CAGR: +8.4%

TSMC Local Procurement

68%

2030 Local Procurement Target

Advanced processes and packaging are driving material consumption, while localization is creating more opportunities for domestic materials suppliers.

Sources: Market Research Future, Precedence Research, TSMC 2025 Sustainability Report

*Semiconductor (SEMI)

AI Is Driving Parallel Growth in Advanced Process and Advanced Packaging Product Lines

Advanced Processes

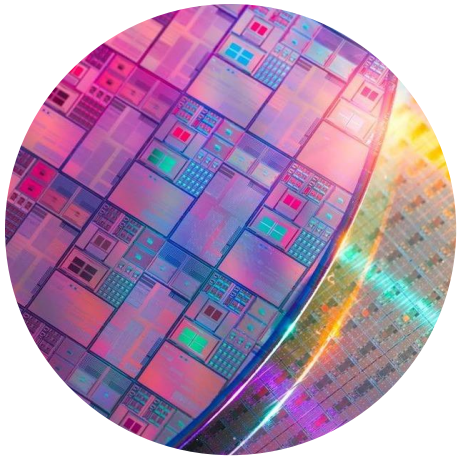
Advanced Nodes / Next-Generation Materials

Wet–Remover A	Post-Dry-Etch Remover
Wet–Etchant B	Copper Etchant
Wet–Stripper B	Photoresist Stripper

Mature Processes

Localization of Wet Process / Lithography Materials

Litho–Polymer A/B/C	Polymers for Photoresists
Litho–Thinner	High-Purity Solvent
Wet–Stripper	BARC Stripper



Specialty Chemicals Key Product Lines

Advanced Packaging

Capacity Expansion for AI Chip 2.5D / 3D ICs

Specialty–RL	Laser Release Layer
Wet–Etchant A	Copper Etchant
Wet–Stripper A	Photoresist Stripper
PSPI	Photosensitive Dielectric

Display Materials

Global Leadership in PS and PSA PI Market Share

PS	Photo Spacer
PSA PI	Liquid Crystal Alignment Layer
Cu Etchant	Copper Etchant

Stable Display Materials Business and Strong Growth in Semiconductor Materials

*Semiconductor (SEMI)

Key Products Have Entered Mass Production for Advanced Packaging and Advanced Processes

Advanced Packaging

Specialty–RL

Laser Release Layer

In-house Development | Mass Production
Two-in-One: One Layer Replaces a Two-Layer Process

Advanced Packaging

Wet–Etchant B

High-Selectivity Copper Etchant

In-house Development | Mass Production
Entered mass production in 2025

Advanced Processes

Wet–Remover A

Post-Dry-Etch Cleaner

In-house Development | Mass Production
Entered mass production in 2025

Mature Processes

Litho–Polymer A/B/C

High-Purity Polymers for Photoresists

Strategic Partnership | Mass Production
Synthesized for a leading international materials company

Advanced Processes

2 nm Process Materials

2 Products

In-house Development | Strategic Partnership | Mass Production
Qualified for customer 2 nm processes

Display

PSA PI

Liquid Crystal Alignment Layer

In-house Development | Mass Production
Became a first source, breaking Japanese suppliers' dominance

*Semiconductor (SEMI)

Expanding Our Product Portfolio Through Diverse Collaboration Models



8

New Products
In-house Development | Joint Development

6

Strategic Partnerships with International Chemical Companies

Collaboration Models- Win-Win Strategy :

Joint development and diverse collaboration models

Precision Manufacturing :

Formulation, synthesis, and purification

Materials Foundry :

Partner-led R&D, DAXIN manufacturing

Note: The 5 products entering line qualification in 2H 2026 are included in the validation pipeline. Of the mass-produced products, 7 are internally developed and 6 are developed through strategic partnerships.

Chungkang Capacity Expansion and the New Facility in Ciaotou Science Park Will Drive Semiconductor Growth

Taichung **Central Taiwan Science Park Facility**

Corporate Headquarters, R&D Center, Semiconductor Materials, and Display Materials

Taichung **Chungkang Plant 1**

Display Materials and Semiconductor Materials

Taichung **Chungkang Plant 2**

Semiconductor: Approx. 10 lines on 1F;
New lines under construction on 2F; 3F–4F space ready

Kaohsiung **Ciaotou Science Park Facility (Planned)**

Advanced Semiconductors & Key Raw Materials;
NT$2.2 billion investment, expected to contribute from 2029

31.4%

Overseas Revenue Contribution (3Q 2026; 2025: 36.0%)

China

Local Supply of LCD Materials

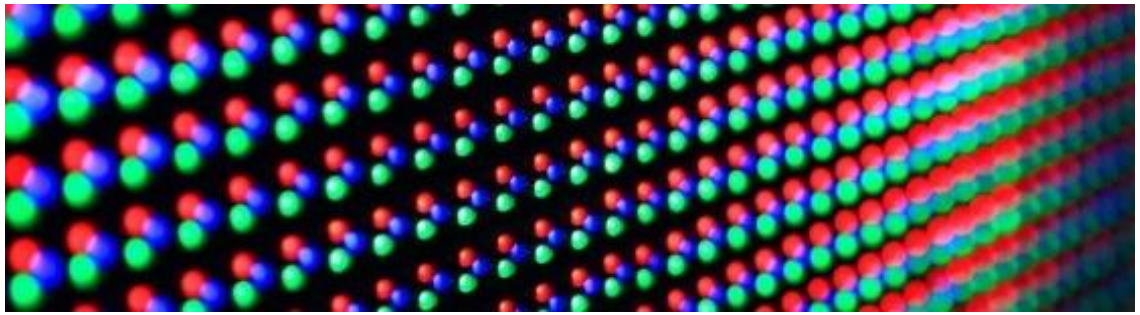
U.S. Customer Sites

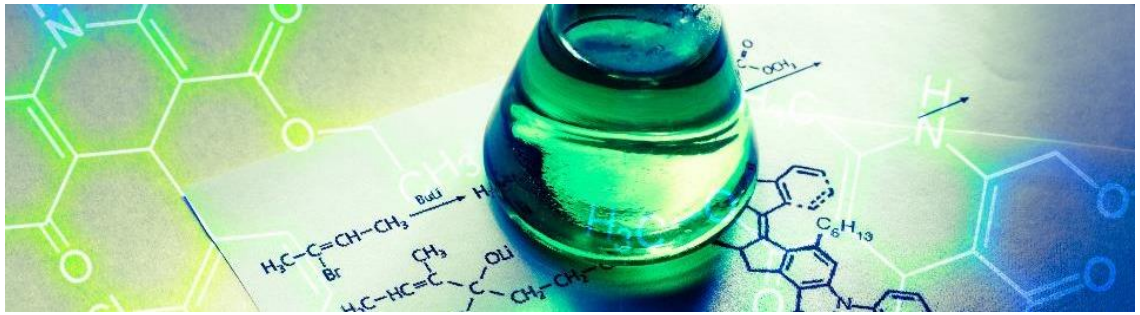
Supplied from Taiwan; local production under evaluation

Production Line Setup

4–6 months per line; construction begins during the qualification stage

Display Materials:
Expanding into Higher-Value Applications





70.9%

3Q 2026 Revenue Contribution

Display Materials: Moving Up the Value Chain

- Global leadership in PS and PSA PI market share
- PSA PI introduced at a new mass-production site; ramp-up of e-paper alignment film
- Low-temperature ESG materials, gaming, and MicroLED optical communication materials

2.0%

3Q 2026 Revenue Contribution

Key Raw Materials & Others: New Applications

- High-performance monomers, high-purity polymers, silicon-anode polymers, and silicone hydrogel
- Low-Dk / Df materials progressing through qualification
- Developing materials for AI substrates, thermal management, and electric vehicles

03 Competitiveness

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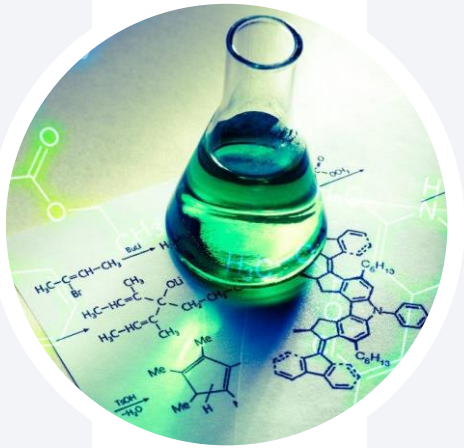
Multiple Competitive Advantages

R&D Resources

> 50%

Share of Employees in R&D

R&D spending accounts for 10–12% of revenue; among the highest PhD employee ratios in the industry



Upstream Synthesis

341

Granted Patents

In-house synthesis of key monomers and polymers, with supply to industry peers

Qualification Barrier

Approx. 2–3 Years

From Release Layer Development to Qualification Completion

Dedicated production lines; long-term customer partnerships after qualification and adoption

Economies of Scale

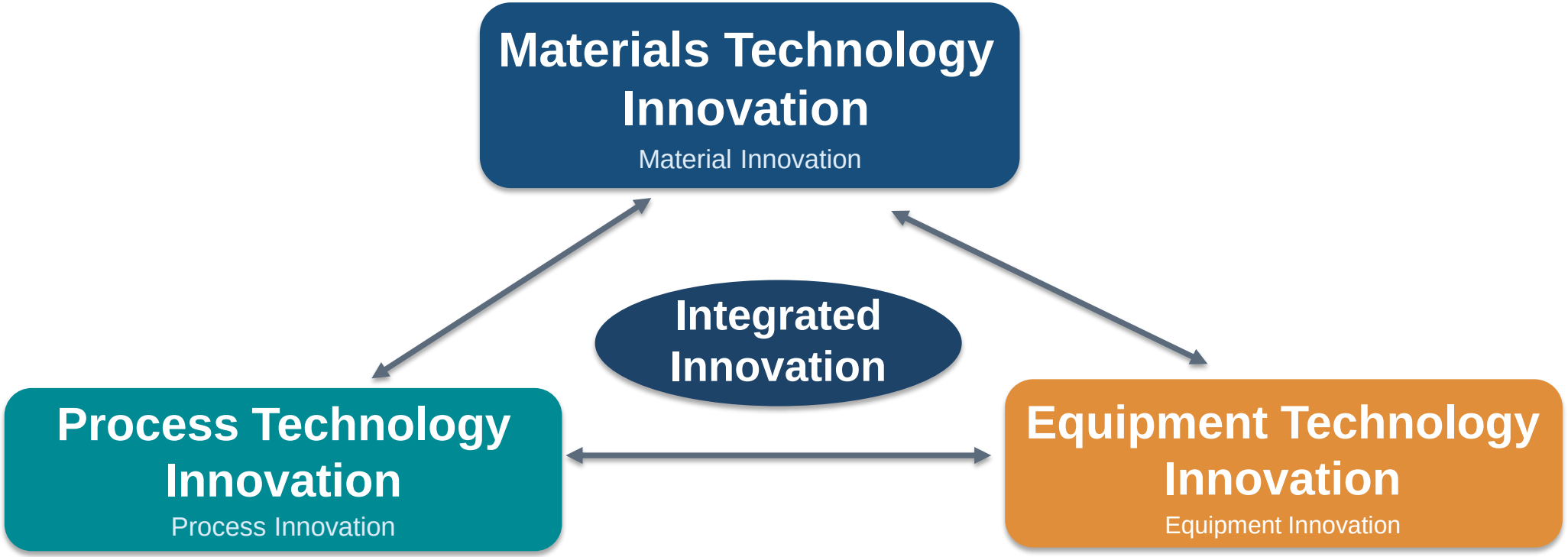
Leading Market Share

Photo Spacer (PS)

Release Layer

Three Technological Innovations Build Our Core Competitive Advantages

Integrating three technology innovations to continuously overcome established limitations in materials and manufacturing



Creating differentiated products that competitors find difficult to replicate

Unique Product Value × Technological Barriers × Long-Term Competitive Advantage

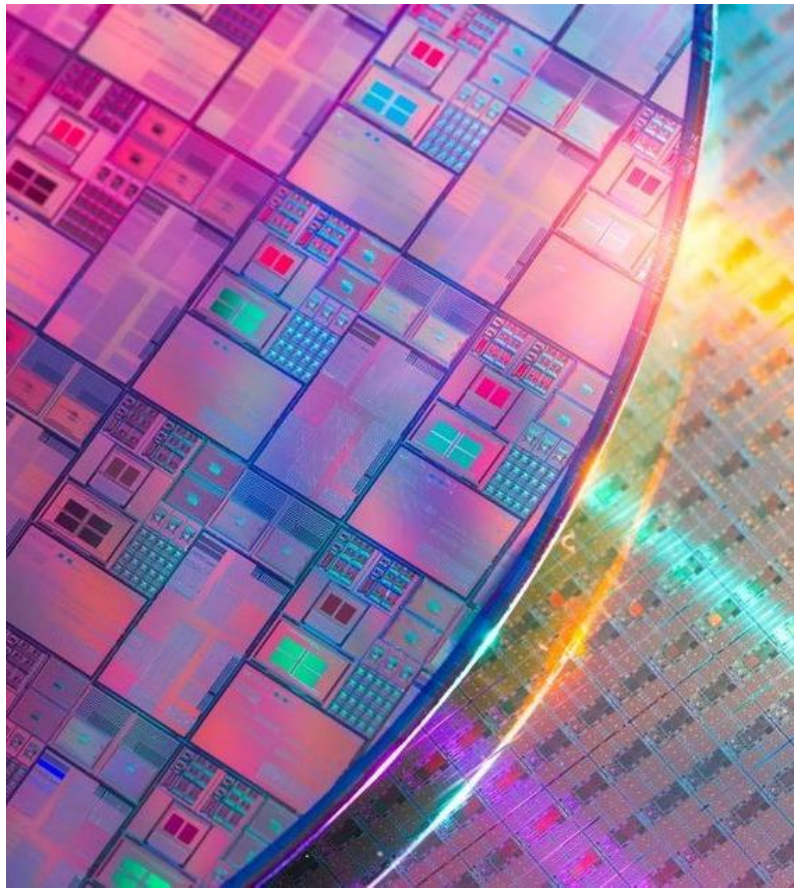
04 Outlook

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New Product Launches to Drive Growth in 2027

2027 Operating Targets: Maintain Double-Digit Revenue Growth | Improve Profitability



New Product Mass Production Ramp-Up

Multiple new products scheduled to enter mass production in 2027;
at least 10 additional production lines planned for construction in 2027

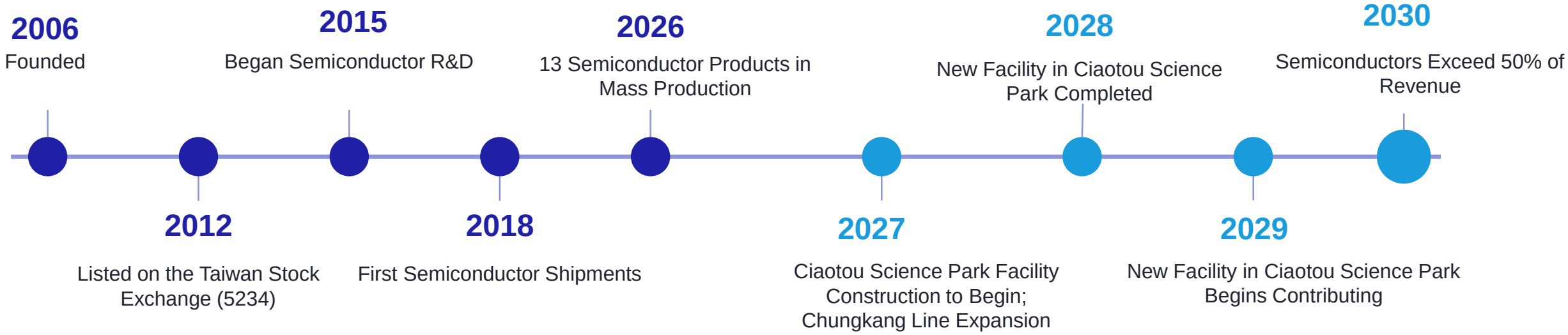
Expanded Adoption in Advanced Nodes & Packaging

Broader POR adoption in line with customers' next-generation process nodes and advanced packaging applications

Diversified Strategic Partnerships

Expanding collaborations with leading international chemical companies from single-product engagements to joint development initiatives.

New Facility in Ciaotou Science Park to Begin Mass Production in 2029



Chungkang Line Expansion

Space on 2F–4F is ready; each line takes 4–6 months to set up

New Ciaotou Science Park Facility

NT$2.2 billion (excluding equipment); construction starts in 1Q 2027, contribution expected in 2029

Overseas Support

U.S. customers supplied from Taiwan; local production under evaluation

Q & A

Thank You for Your Attention

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